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EFS ID: 60526
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Title of Invention: PLASTIC INTEGRATED CIRCUIT
PACKAGE AND METHOD AND
LEADFRAME FOR MAKING THE
PACKAGE
First Named Inventor: THOMAS GLENN
Domestic/Foreign Application: Domestic Application
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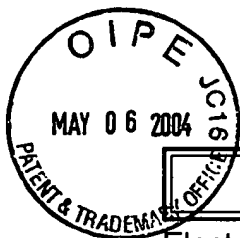
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**TRANSMITTAL**

Electronic Version v1.1

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Title of Invention	PLASTIC INTEGRATED CIRCUIT PACKAGE AND METHOD AND LEADFRAME FOR MAKING THE PACKAGE							
Application Number: 10/626150 Date: 2003-07-24 First Named Applicant: THOMAS P. Confirmation Number: 9302 Attorney Docket Number: AMKOR007C2								
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids2-usidst.xml us-ids.dtd us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids2-usidst.xml us-ids.dtd us-ids.xsl		
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<h3>US Patent Documents</h3> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>5216278</td><td>1993-06-01</td><td>Lin et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>2</td><td>5218231</td><td>1993-06-08</td><td>Kudo</td><td></td><td></td><td></td></tr><tr><td></td><td>3</td><td>5221642</td><td>1993-06-22</td><td>Burns</td><td></td><td></td><td></td></tr><tr><td></td><td>4</td><td>5250841</td><td>1993-10-05</td><td>Sloan et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>5</td><td>5252853</td><td>1993-10-12</td><td>Michii</td><td></td><td></td><td></td></tr><tr><td></td><td>6</td><td>5258094</td><td>1993-11-02</td><td>Furui et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>7</td><td>5266834</td><td>1993-11-30</td><td>Nishi et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>8</td><td>5273938</td><td>1993-12-28</td><td>Lin et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>9</td><td>5277972</td><td>1994-01-11</td><td>Sakumoto et al.</td><td></td><td></td><td></td></tr><tr><td></td><td>10</td><td>5278446</td><td>1994-01-11</td><td>Nagaraj et al.</td><td></td><td></td><td></td></tr></tbody></table>		init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	5216278	1993-06-01	Lin et al.					2	5218231	1993-06-08	Kudo					3	5221642	1993-06-22	Burns					4	5250841	1993-10-05	Sloan et al.					5	5252853	1993-10-12	Michii					6	5258094	1993-11-02	Furui et al.					7	5266834	1993-11-30	Nishi et al.					8	5273938	1993-12-28	Lin et al.					9	5277972	1994-01-11	Sakumoto et al.					10	5278446	1994-01-11	Nagaraj et al.			
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Signature

Examiner Name	Date